24-Pin SOIC-to-22-Pin 0.400" DIP

FEATURES
- A cost-effective means of upgrading to SOIC without changing your PCB layout.

GENERAL SPECIFICATIONS
- BOARD MATERIAL: 0.062 thick FR-4 with 1-oz. Cu traces, both sides
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200µ [5.08µ] Sn/Pb 93/7 per ASTM B579-73 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221ºF [105ºC]

MOUNTING CONSIDERATIONS
- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71±0.08] dia.

ALL DIMENSIONS: INCHES [MILLIMETERS]
ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED
PINS 11 AND 14 NOT CONNECTED ON SOIC
CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION
22-304504-18-P
Optional Panelized Version